



# Material Composition Declaration

## EPC2106

Company Name	Efficient Power Conversion (EPC)	Issue Date:	9/22/2017
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	3.0 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	2.6104	87.5146	90.0922	875146
	Silicon oxide	7631-86-9	0.0117	0.3918		3918
	Silicon nitride	12033-89-5	0.0039	0.1310		1310
	Gallium nitride	25617-97-4	0.0135	0.4510		4510
	Aluminum	7429-90-5	0.0203	0.6795		6795
	Aluminum nitride	24304-00-5	0.0033	0.1090		1090
	Titanium	7440-32-6	0.0004	0.0145		145
	Titanium nitride	25583-20-4	0.0017	0.0569		569
	Copper	7440-50-8	0.0007	0.0226		226
	Tungsten	7440-33-7	0.0005	0.0178		178
	Polyimide		0.0210	0.7033		7033
Under Bump Metal	Titanium	7440-32-6	0.0002	0.0060	0.5094	60
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.0150	0.5034		5034
Solder Bump	Tin	7440-31-5	0.2677	8.9754	9.3984	89754
	Silver	7440-22-4	0.0112	0.3759		3759
	Copper	7440-50-8	0.0014	0.0470		470
Sum in total:			2.9829	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.